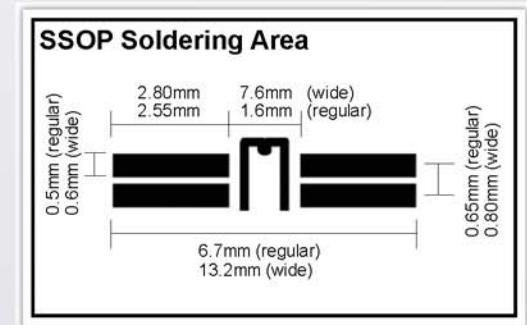
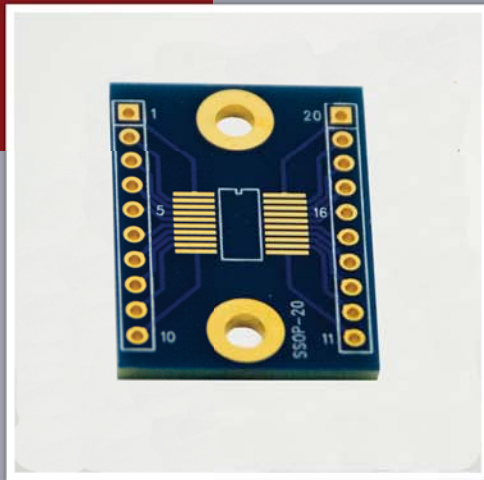


SSOP/TSSOP Prototyping board

PT-SSOP



The T/SSOP prototyping boards are designed to allow quick and easy circuit prototyping of chips using the SSOP or TSSOP Package. Solutions are available for both regular and wide package types. The boards also offer 0.08" round pads with 0.047" plated holes spaced 0.1" apart which can be used to solder DIP headers or wires to interface with the chip. The spacing of the holes also allows the boards to be connected to a standard 0.1" pitch bread-board with ease.

Ordering Information

Part Number	No. of Pads	Board Dimensions
PT-SSOP-8	8	0.85" x 0.82"
PT-SSOP-16	16	1.00" x 0.82"
PT-SSOP-20	20	1.15" x 0.82"
PT-SSOP-24	24	1.30" x 0.82"
PT-SSOP-28	28	1.45" x 0.82"
PT-SSOP-36	36	1.85" x 0.82"
PT-SSOP-36W	36 wide	1.85" x 0.82"
PT-SSOP-44	44	2.45" x 0.82"
PT-SSOP-44W	44 wide	2.45" x 0.82"
PT-SSOP-48	48	2.45" x 0.82"
PT-SSOP-48W	48 wide	2.45" x 0.82"
PT-SSOP-56W	56 wide	2.90" x 0.82"

T/SSOP Pad Pitch:
0.65mm (regular)
0.80mm (wide)

Hole Diameter:
0.047" (1.2mm)
plated holes

Hole Spacing:
0.1" (2.54mm)

T/H Pad:
0.08" (2.032mm)
round pad

Type/Finish:
FR-4 with
Electroless Nickel
Immersion Gold
(ENIG)

PCB Thickness:
0.062" (1.57mm)

Mounting Holes:
4-40 size, plated